

SHENZHEN MENGKE ELECTRONICS TECHNOLOGY CO.,LTD TO-252/251 Plastic-Encapsulate MOSFETS

MK5006N

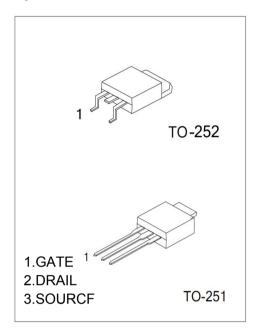
N-Channel 60-V(D-S) Power MOSFET

| V(BR)DSS | RDS(on)MAX | ID |
|----------|------------|-----|
| 60 V | 20mΩ@ 10 V | 50A |

General Description:

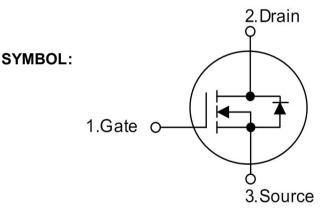
The high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition , this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes . The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power suppliers, converters and PWM motor controls , these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

Equivalent Circuit:



FEATURE:

- Power switching application
- * Hard switched and high frequency circuits
- W Uninterruptible power supply
- ※ Fully characterized avalanche voltage and current
- ※ Excellent package for good heat dissipation
- Good stability and uniformity with high EAS



Maximum ratings (Ta=25 $^{\circ}$ C unless otherwise noted)

| Parameter | Symbol | Value | Unit |
|---|--------|----------|------------------------|
| Drain-Source Voltage | VDS | 60 | ٧ |
| Gate-Source Voltage | VGS | ±20 | V |
| Continuous Drain Current | ID | 50 | ^ |
| Pulsed Diode Curren | IDM | 150 | Α |
| Power Dissipation | PD | 136 | W |
| Thermal Resistance from Junction to Ambient (t≤10s) | RθJA | 100 | °C/W |
| Operating Junction | TJ | 150 | % |
| Storage Temperature | TSTG | -55~+150 | $^{\circ}\!\mathbb{C}$ |



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MOSFET ELECTRICAL CHARACTERISTICS

Static Electrical Characteristics (Ta = 25 ℃ Unless Otherwise Noted)

| Parameter | Symbol | Test Condition | Min | Тур | Max | Unit |
|---------------------------------------|----------|---|-----|------|------|------|
| Static | | | | | I. | I. |
| Drain-source breakdown voltage | V(BR)DSS | VGS = 0V, ID = 250μA | 60 | | | V |
| Gate-source threshold voltage | VGS(th) | VDS =VGS, ID = 250μA | 1.2 | | 2.5 | V |
| Gate-source leakage | IGSS | VDS =0V, VGS = ±20V | | | ±100 | nA |
| Zero gate voltage drain current | IDSS | VDS = 60V, VGS =0V | | | 1 | μΑ |
| Drain-source on-state resistancea | RDS(on) | VGS = 10V, ID = 30A | | 14.5 | 20 | mΩ |
| Forward transconductancea | gfs | VDS = 25V, ID = 25A | 24 | | | S |
| Diode forward voltage | VSD | IS= 10A, VGS=0V | | 0.8 | 1.3 | V |
| Dynamic | | | | | • | • |
| Input capacitance | Ciss | | | 900 | | pF |
| Output capacitance | Coss | VDS = 25V,VGS =0V, f=1MHz | | 104 | | pF |
| Reverse transfer capacitanceb | Crss | | | 33 | | pF |
| Total gate charge | Qg | | | 30 | | nC |
| Gate-source charge | Qgs | VDS = 25V,VGS = 10V, ID = 50A | | 10 | | nC |
| Gate-drain charge | Qgd | 15 00/1 | | 5 | | nC |
| Switchingb | | | | | _ | _ |
| Turn-on delay time | td(on) | | | 25 | | ns |
| Rise time | tr | VDD=30 V RL= 25Ω, ID = 25A, VGEN= 10V,Rg= 25Ω | | 5 | | ns |
| Turn-off delay time | td(off) | | | 50 | | ns |
| Fall time | tf | | | 6 | | ns |
| Drain-Source Diode Characteri | stics | | | | | |
| Continuous Source-Drain Diode Current | IS | | | | 50 | Α |
| Pulsed Diode forward Curren | ISM | | | | 220 | Α |

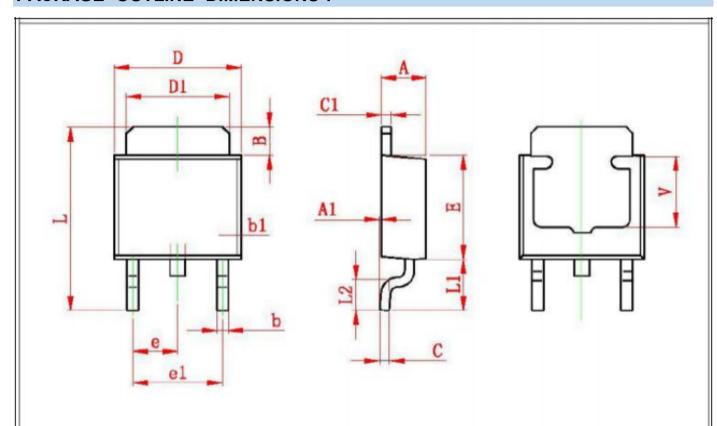
Note:

- 1. Repetitive Rating : Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t < 10 sec.
- 3. Pulse Test : Pulse Width≤300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production testing.



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PACKAGE OUTLINE DIMENSIONS:

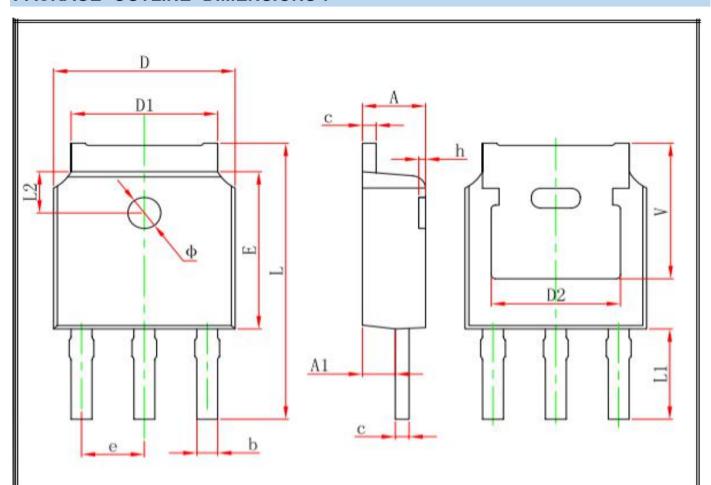


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| Α | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 |
| В | 1.350 | 1.650 | 0.053 | 0.065 |
| b | 0.500 | 0.700 | 0.020 | 0.028 |
| b1 | 0.700 | 0.900 | 0.028 | 0.035 |
| С | 0.430 | 0.580 | 0.017 | 0.023 |
| c1 | 0.430 | 0.580 | 0.017 | 0.023 |
| D | 6.350 | 6.650 | 0.250 | 0.262 |
| D1 | 5.200 | 5.400 | 0.205 | 0.213 |
| E | 5.400 | 5.700 | 0.213 | 0.224 |
| е | 2.300 TYP | | 0.091 TYP | |
| e1 | 4.500 | 4.700 | 0.177 | 0.185 |
| L | 9.500 | 9.900 | 0.374 | 0.390 |
| L1 | 2.550 | 2.900 | 0.100 | 0.114 |
| L2 | 1.400 | 1.780 | 0.055 | 0.070 |
| V | 3.80 REF | | 0.150 | REF |



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| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| Α | 2.200 | 2.400 | 0.087 | 0.094 |
| A1 | 0.860 | 1.160 | 0.034 | 0.046 |
| b | 0.660 | 0.860 | 0.026 | 0.034 |
| С | 0.460 | 0.580 | 0.018 | 0.023 |
| D | 6.500 | 6.700 | 0.256 | 0.264 |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 |
| D2 | 4.830 REF. | | 0.190 REF. | |
| E | 6.000 | 6.200 | 0.236 | 0.244 |
| е | 2.186 | 2.386 | 0.086 | 0.094 |
| L | 10.400 | 11.000 | 0.409 | 0.433 |
| L1 | 3.300 | 3.700 | 0.130 | 0.146 |
| L2 | 1.600 REF. | | 0.063 REF. | |
| Ф | 1.100 | 1.300 | 0.043 | 0.051 |
| h | 0.000 | 0.300 | 0.000 | 0.012 |
| V | 5.350 REF. | | 0.211 | REF. |